

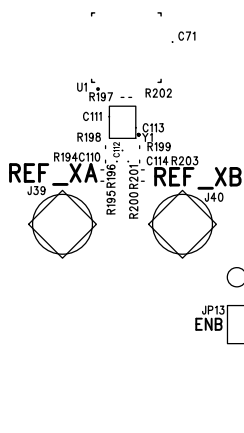
OUT3B J14
R98 . . . C32
R99

J41
OUT9
C167 - C166 - 302 R301

JP23 ENB
JP24 3.3V
EN 3V
2.5V
VDD03 TP16
GND

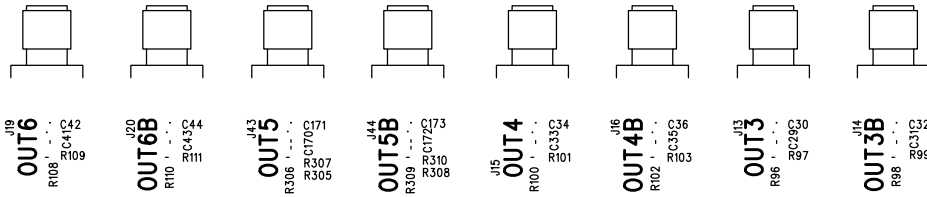
J28
R128 - - -
R129 C59
R127 C60

GND



IN1B

PRIMARY SILKSCREEN



GND



OUT7B
J22
C48
C47
R114
R115



OUT7
J21
C46
C45
R112
R113



OUT8B
J24
C50
C49
R118
R119



OUT8
J23
C50
C49
R116
R117



OUT9B
J42
C169
C168
R302
R303
R304
R315



OUT9
J41
C167
C166
R302
R301



OUT10B
J10
R90
C23
C24



OUT10
J9
R88
C21
C22



OUT11B
J30
R134
C63
C64



OUT11
J29
R131
C61
C62



OUT12B
J12
R94
C27
C28



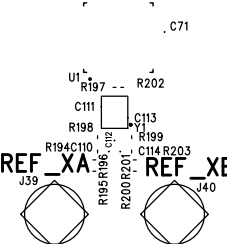
OUT12
J11
R92
C25
C26



OUT13B
J13
R96
C29
C30
R97



OUT13
J13
R96
C29
C30
R97

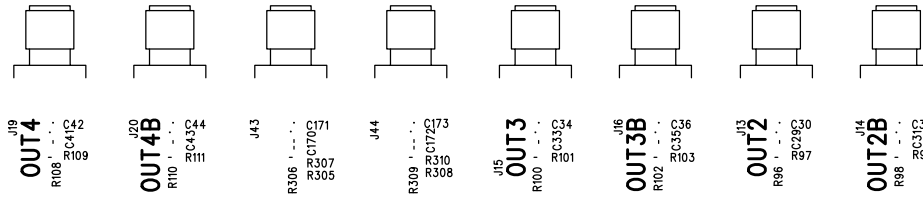


IN2B

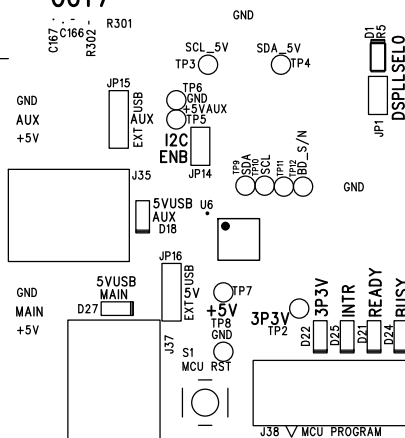
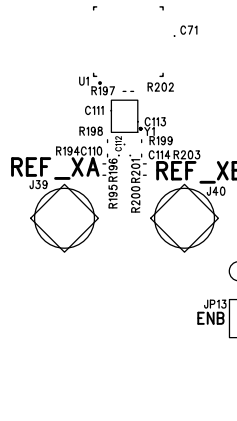
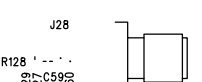
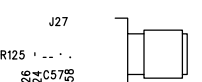
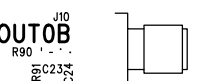
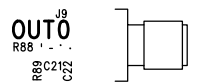
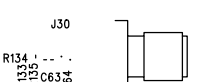
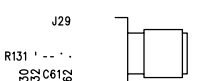
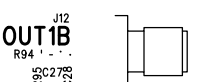
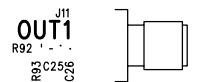
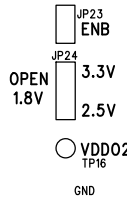
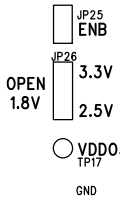
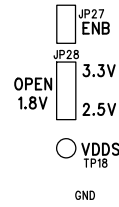
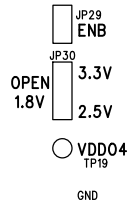
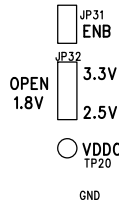
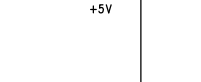
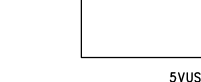
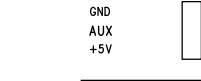
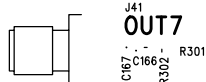
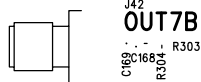
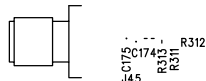
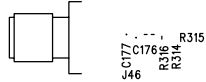
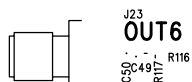
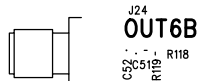
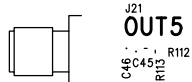
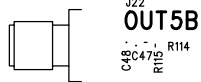
IN2

GND

PRIMARY SILKSCREEN



GND



IN3

IN3B

IN0

IN0B

IN1

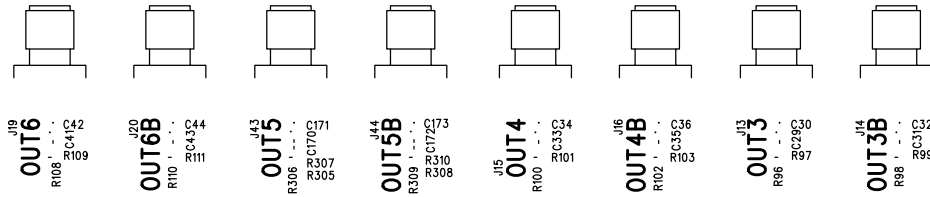
IN1B

IN2B

IN2

GND

PRIMARY SILKSCREEN



GND



OUT7B
J22
C48
C47
R114



OUT7
J21
C46
C45
R112



OUT8B
J24
C50
C49
R118



OUT8
J23
C50
C49
R116



OUT9B
J25
C177
C176
R316
R314
R315



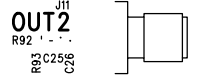
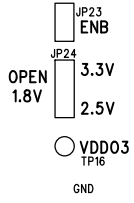
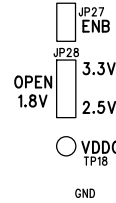
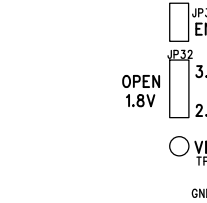
OUT9
J26
C175
C174
R312
R310
R311



OUT9AB
J42
C160
C168
R304
R303



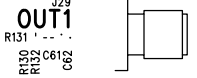
OUT9A
J41
C167
C166
R302
R301



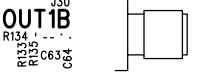
OUT2
J11
R92
C25
C26



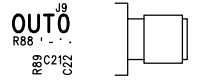
OUT2B
J12
R94
C27
C28



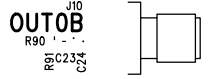
OUT1
J29
R131
R130
C61
C62



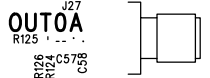
OUT1B
J30
R134
R133
C63
C64



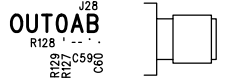
OUT0
J9
R88
R89
C21
C22



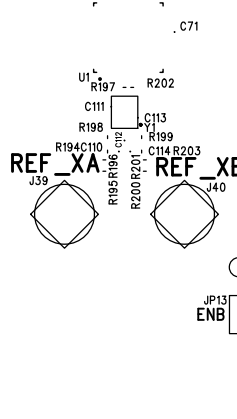
OUT0B
J10
R90
R91
C23
C24



OUT0A
J27
R125
R126
C57
C58

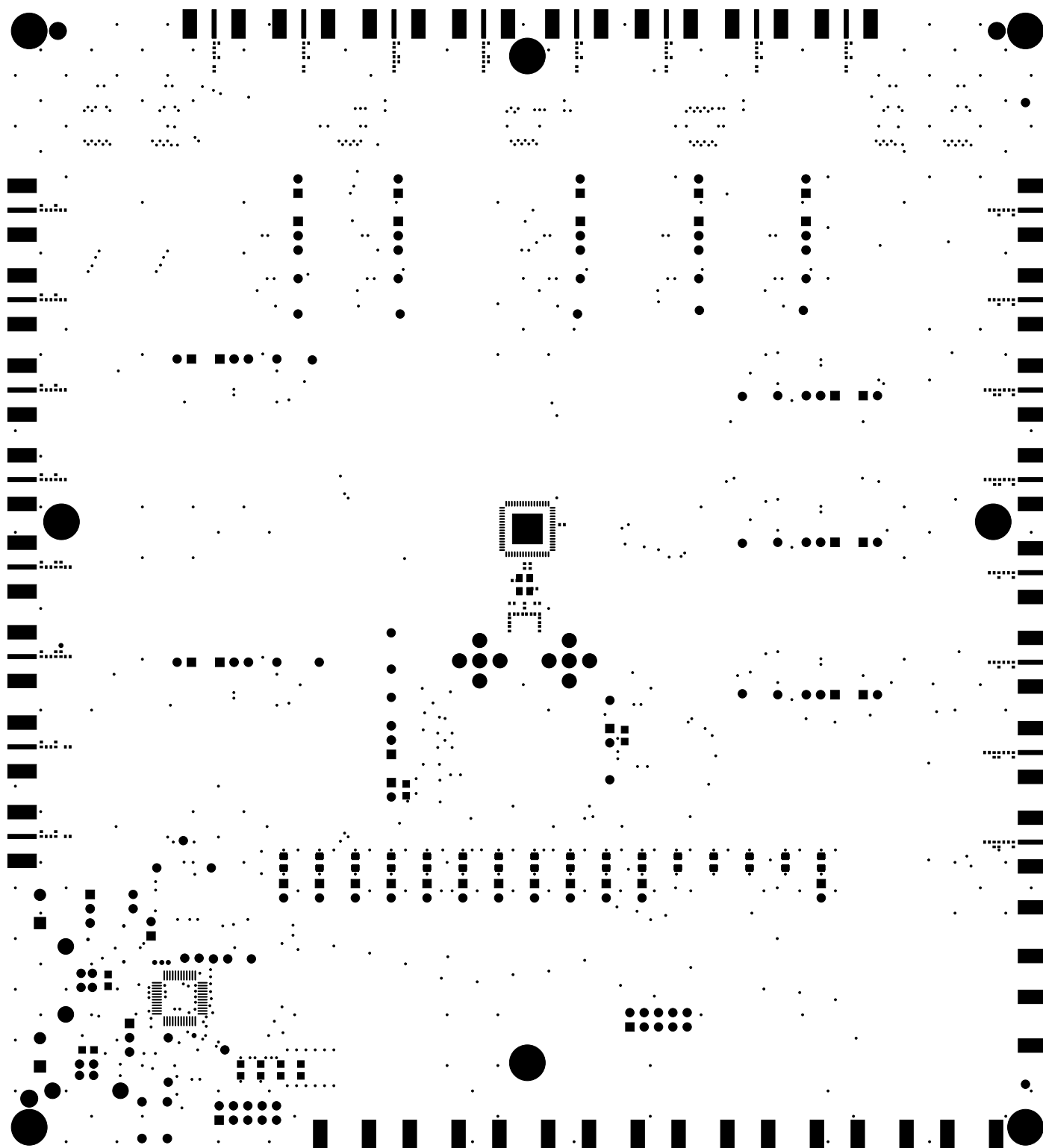


OUT0AB
J28
R128
R129
C59
C60

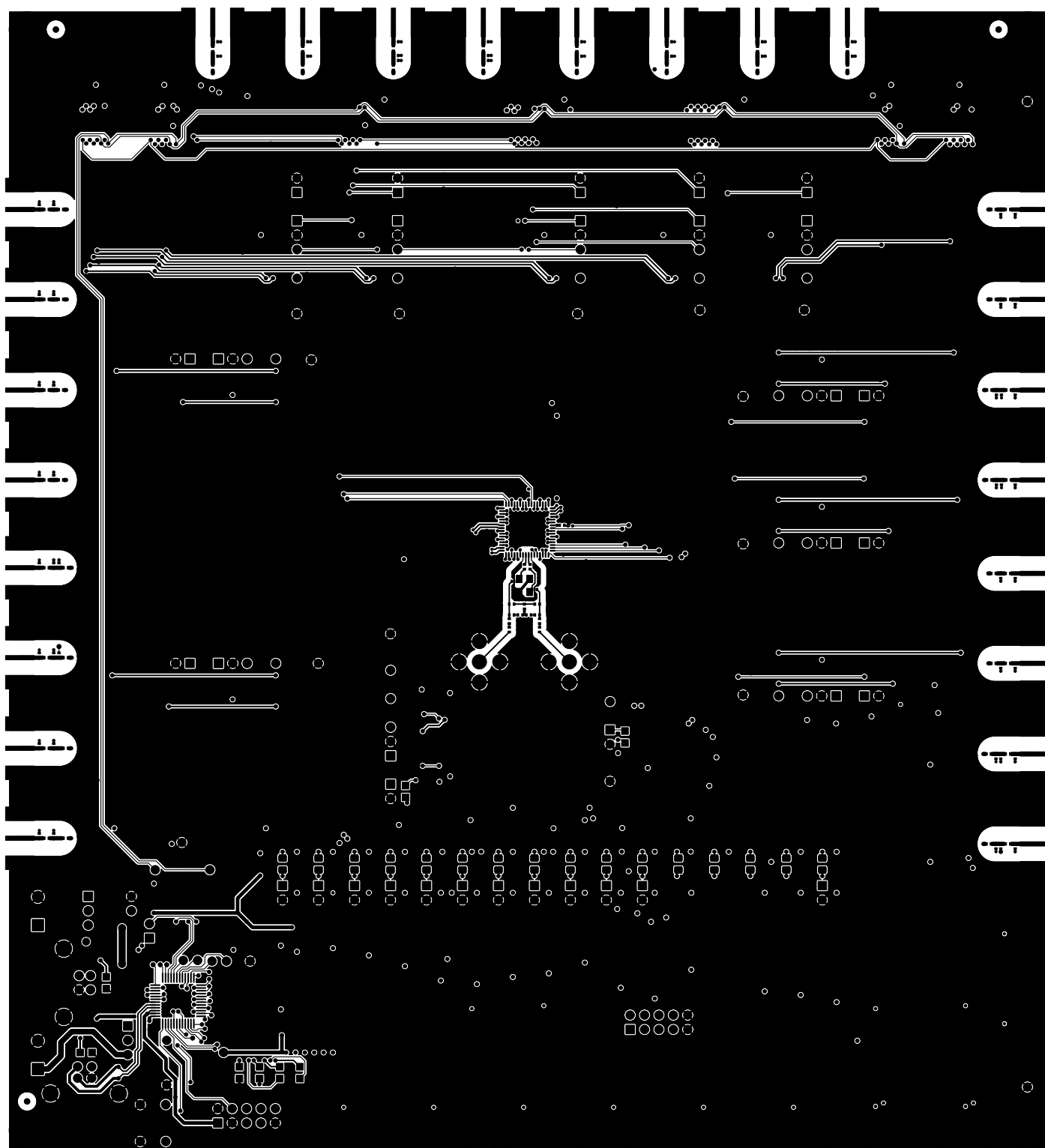




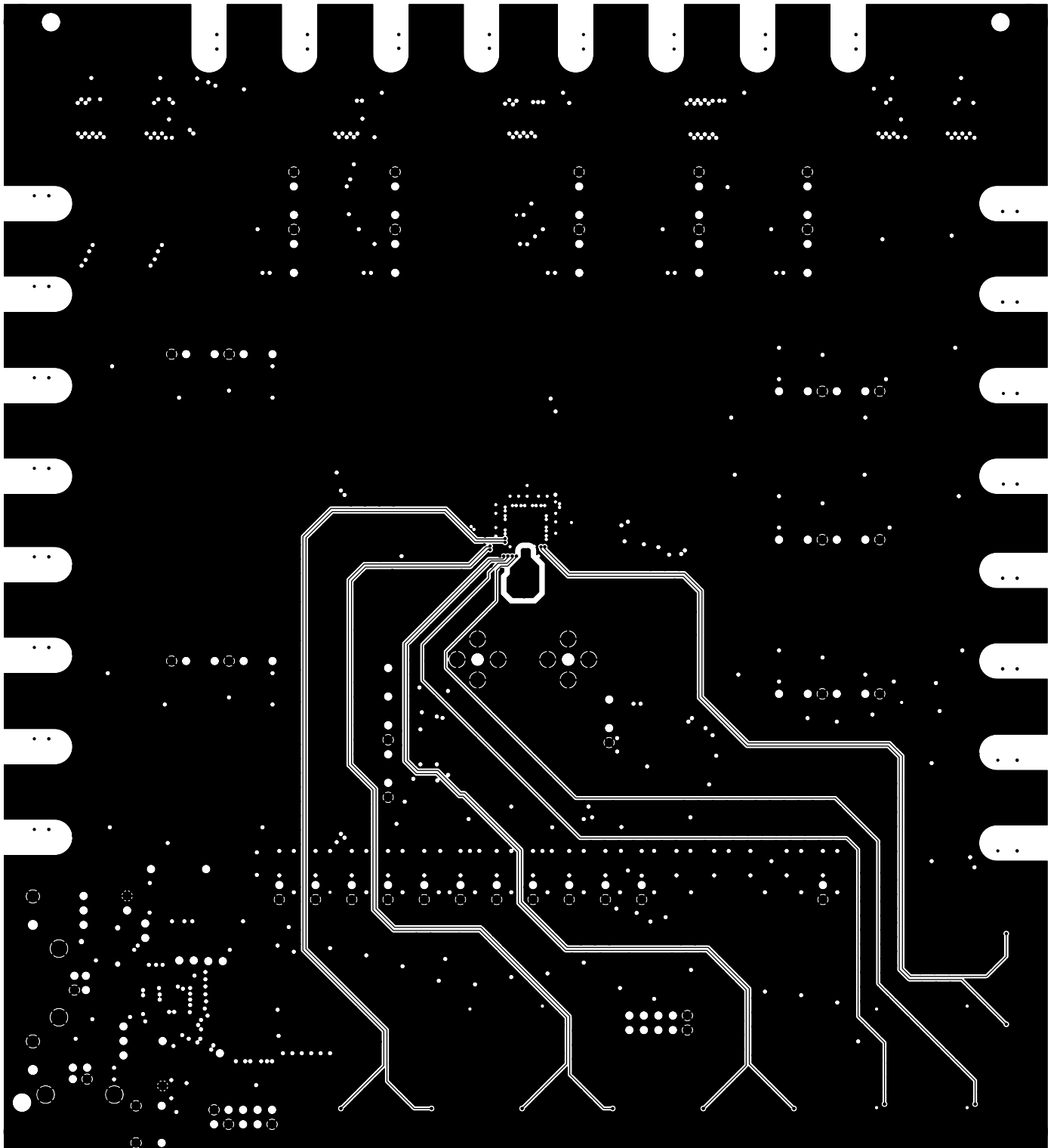
PRIMARY SOLDER MASK



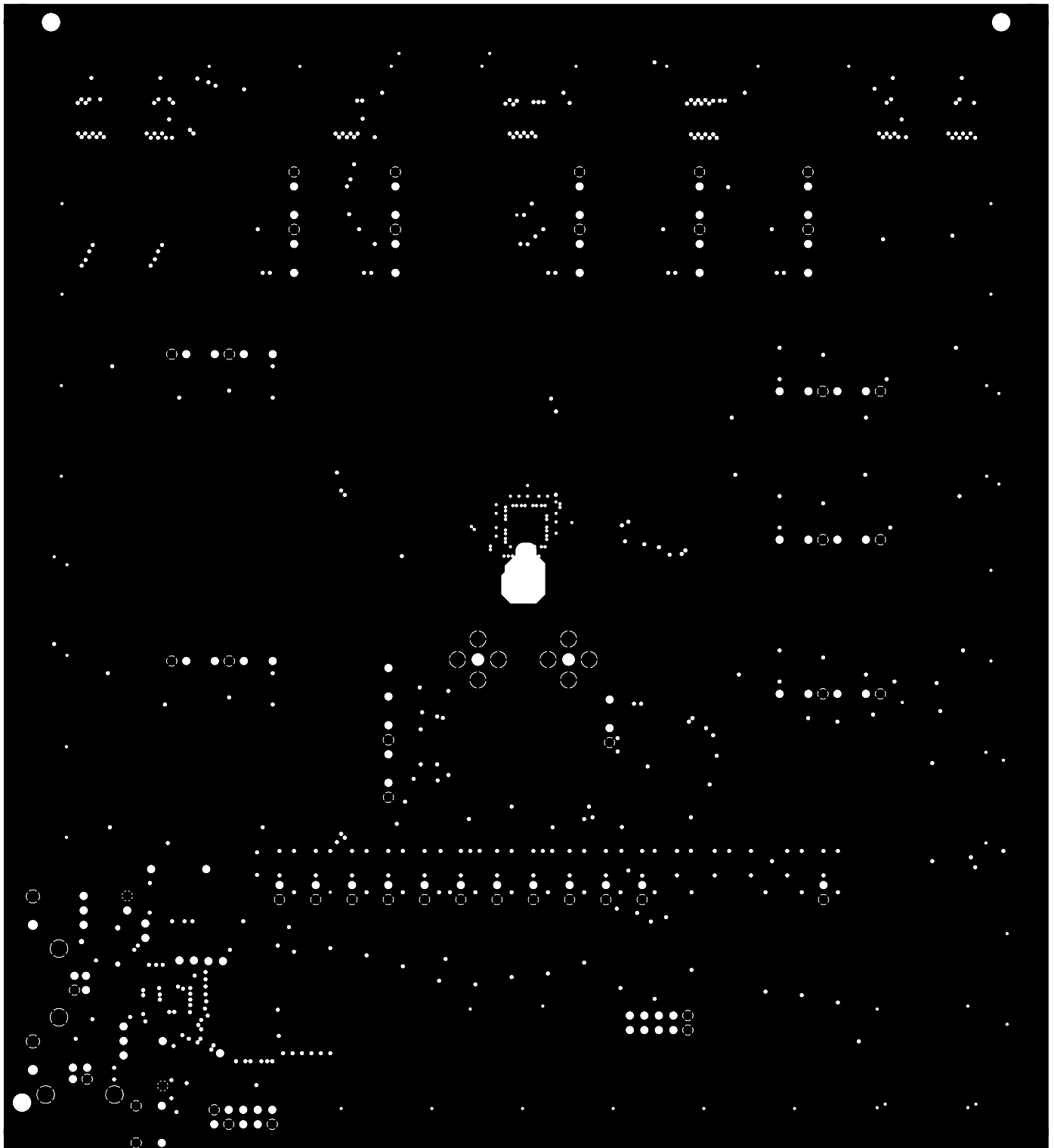
PRIMARY SIDE



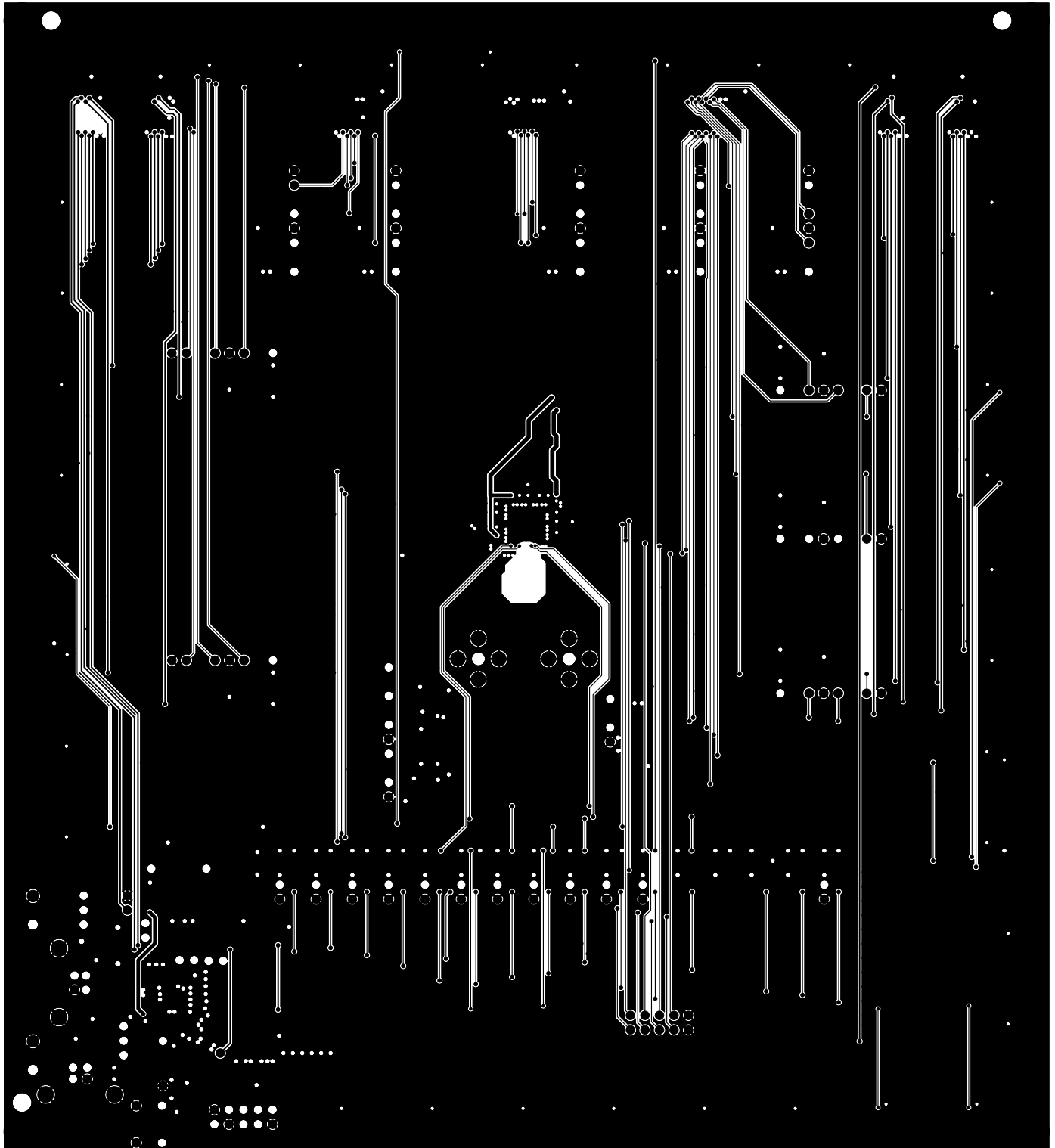
LAYER 02



LAYER 03

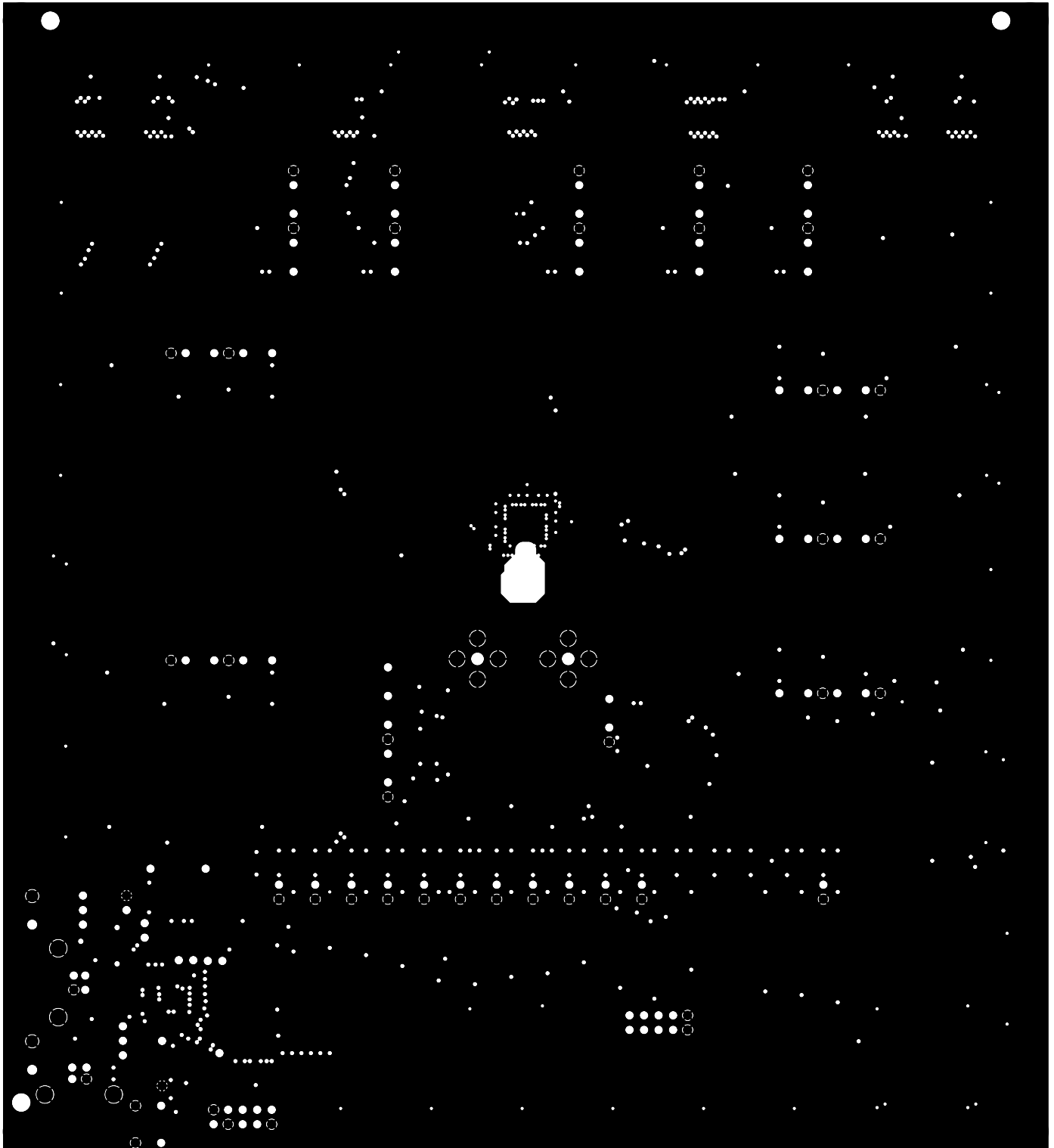


LAYER 04

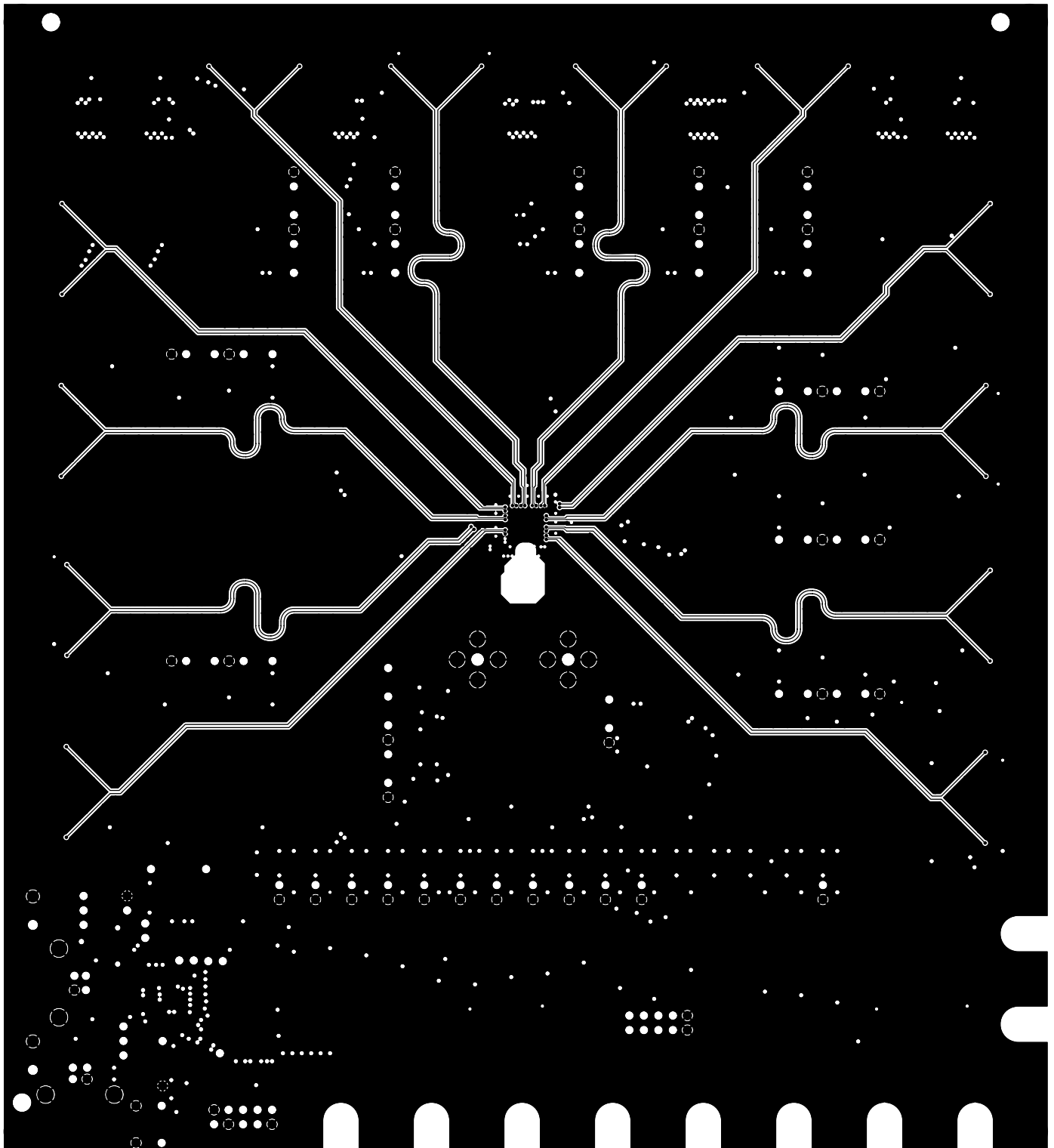




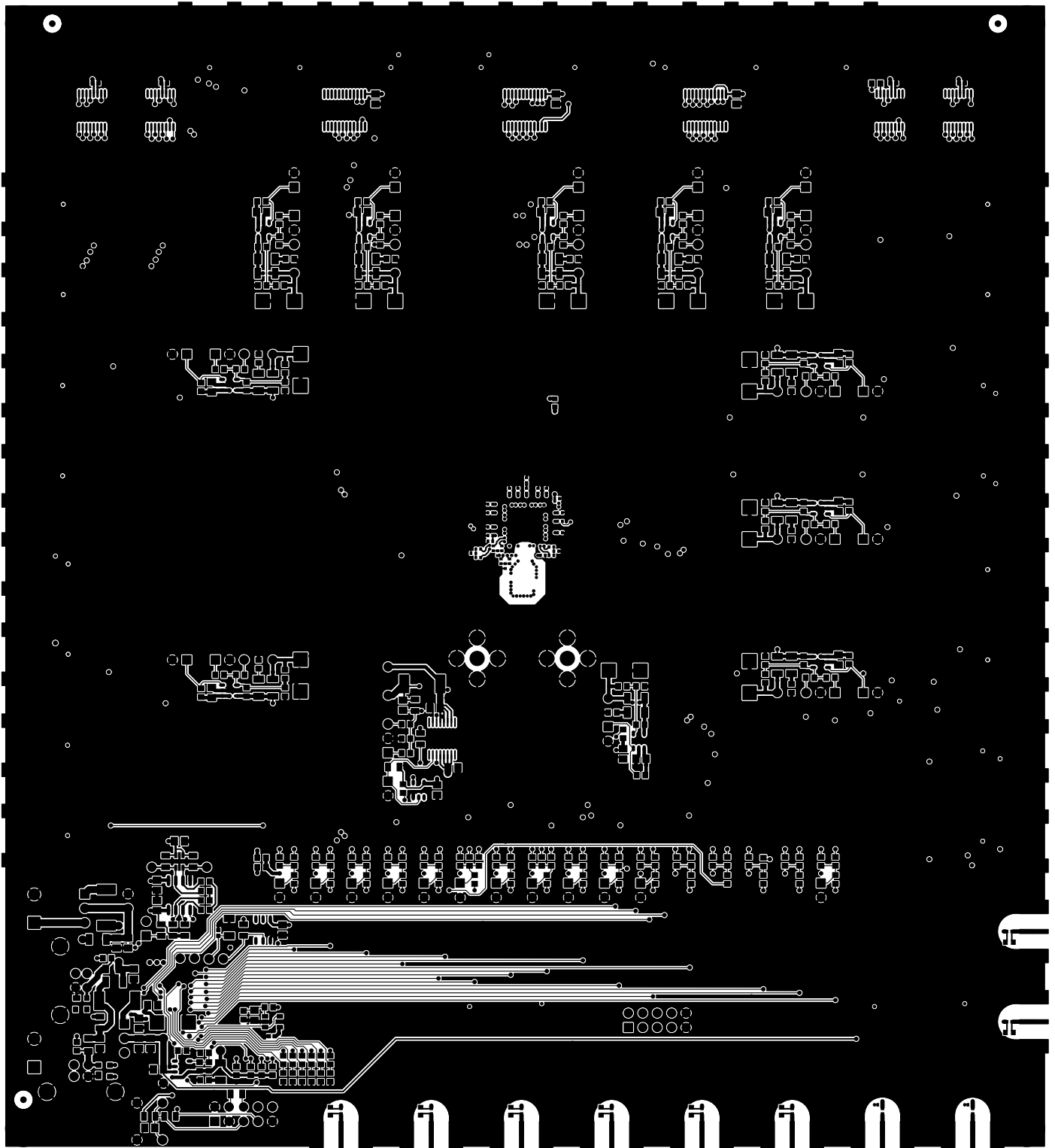
LAYER 06



LAYER 07

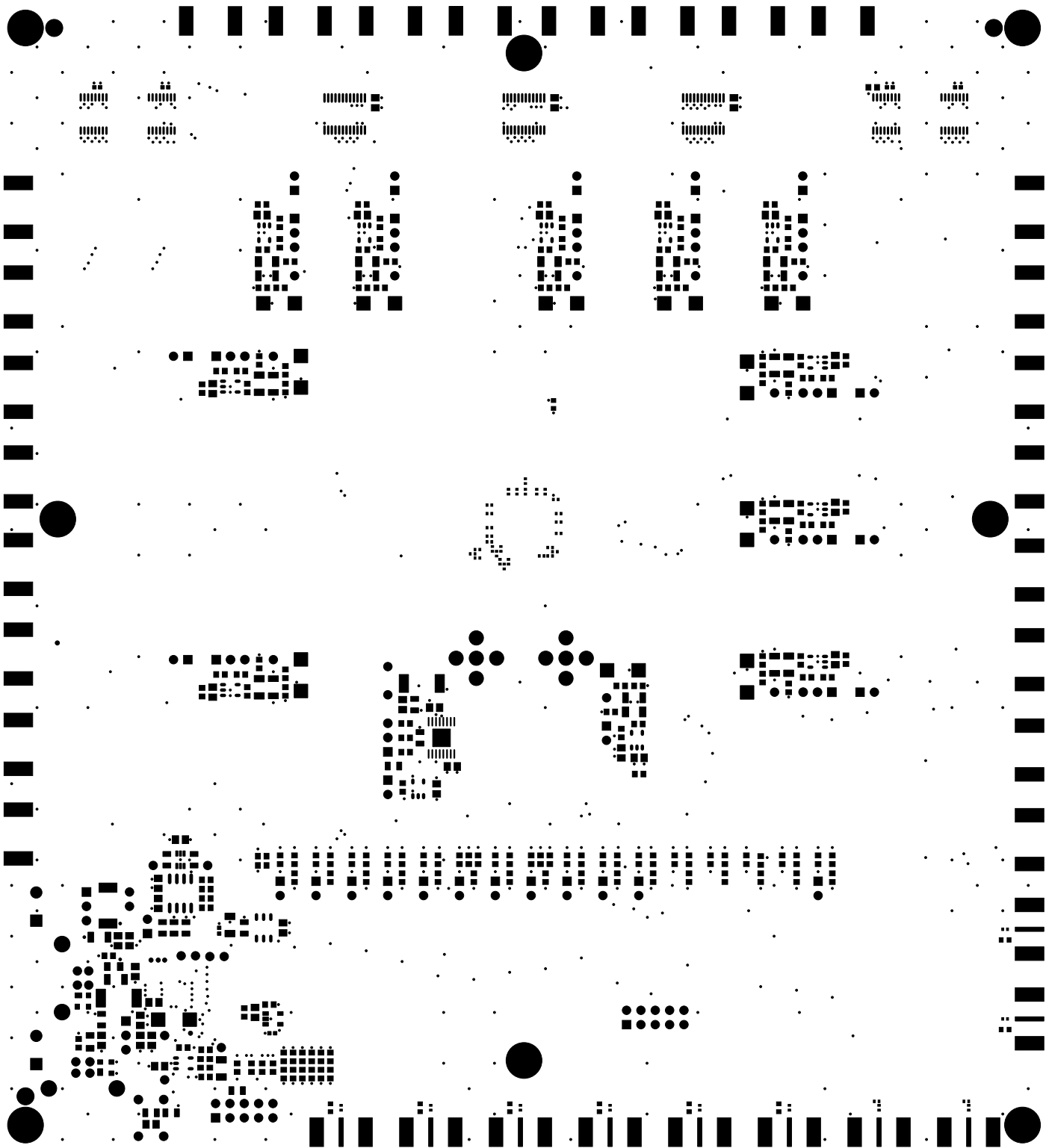


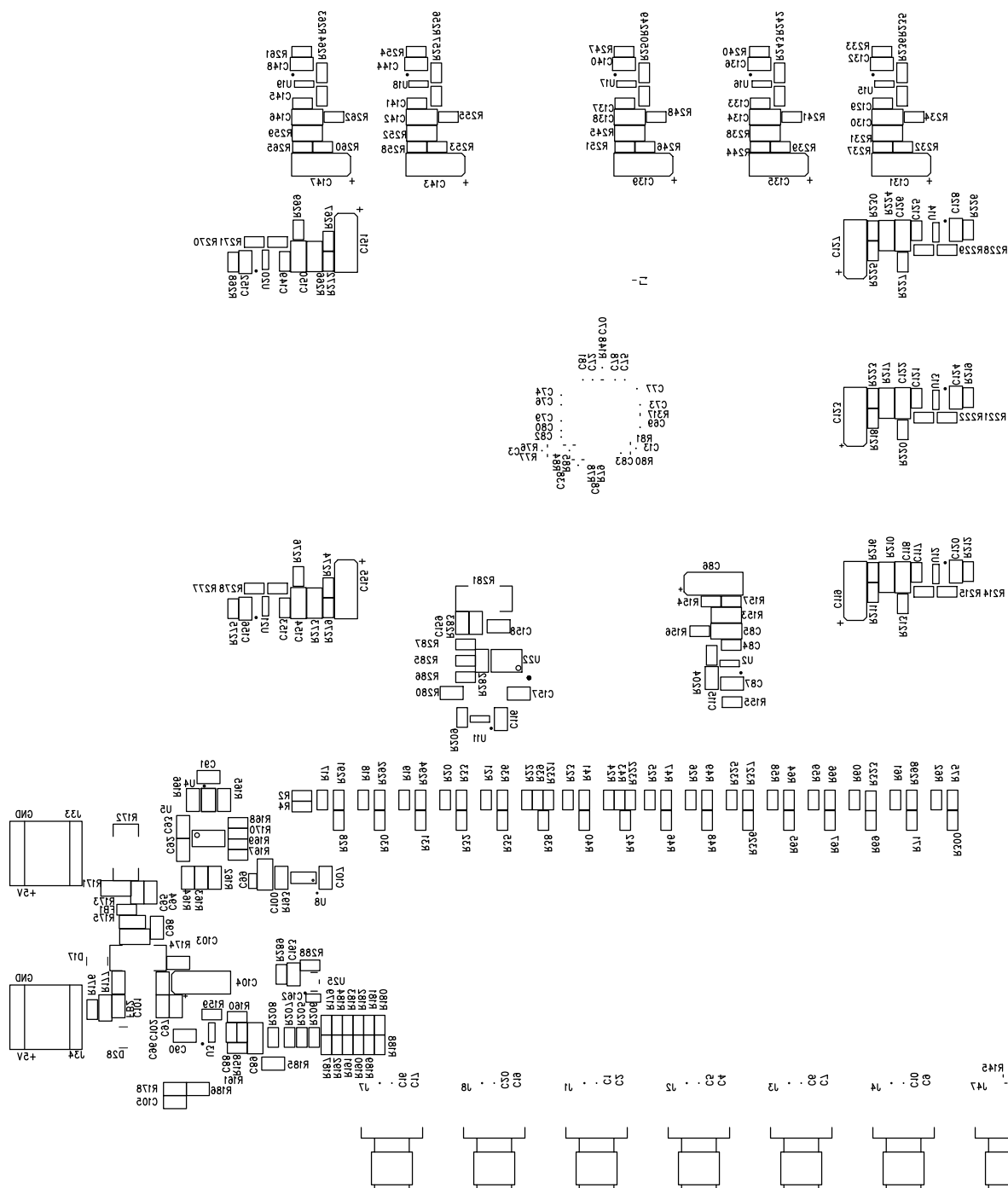
SECONDARY SIDE





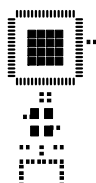
SECONDARY SOLDER MASK





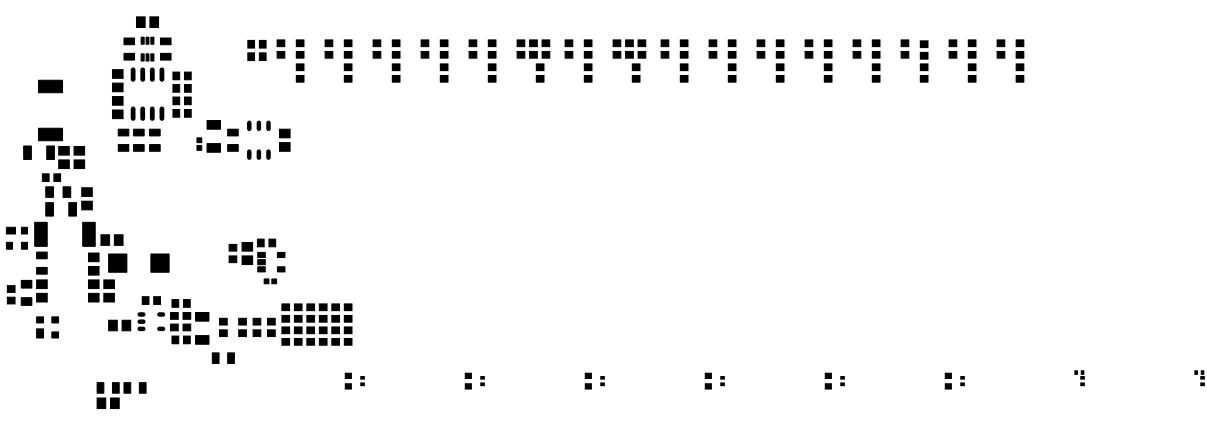
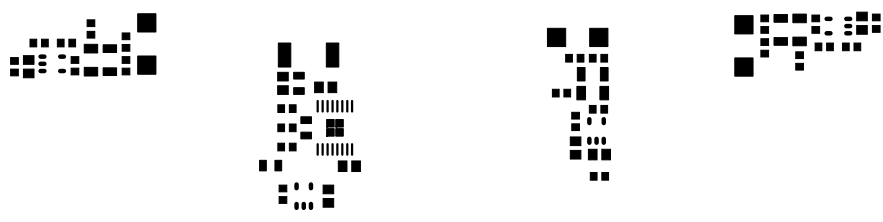
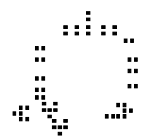
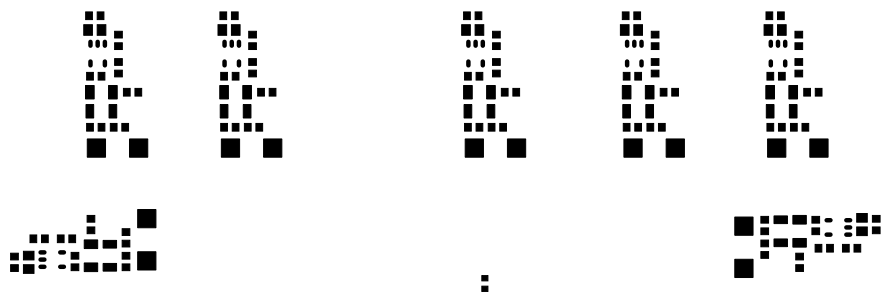
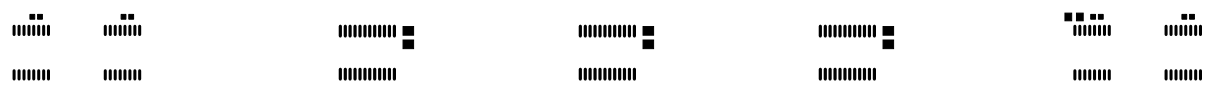


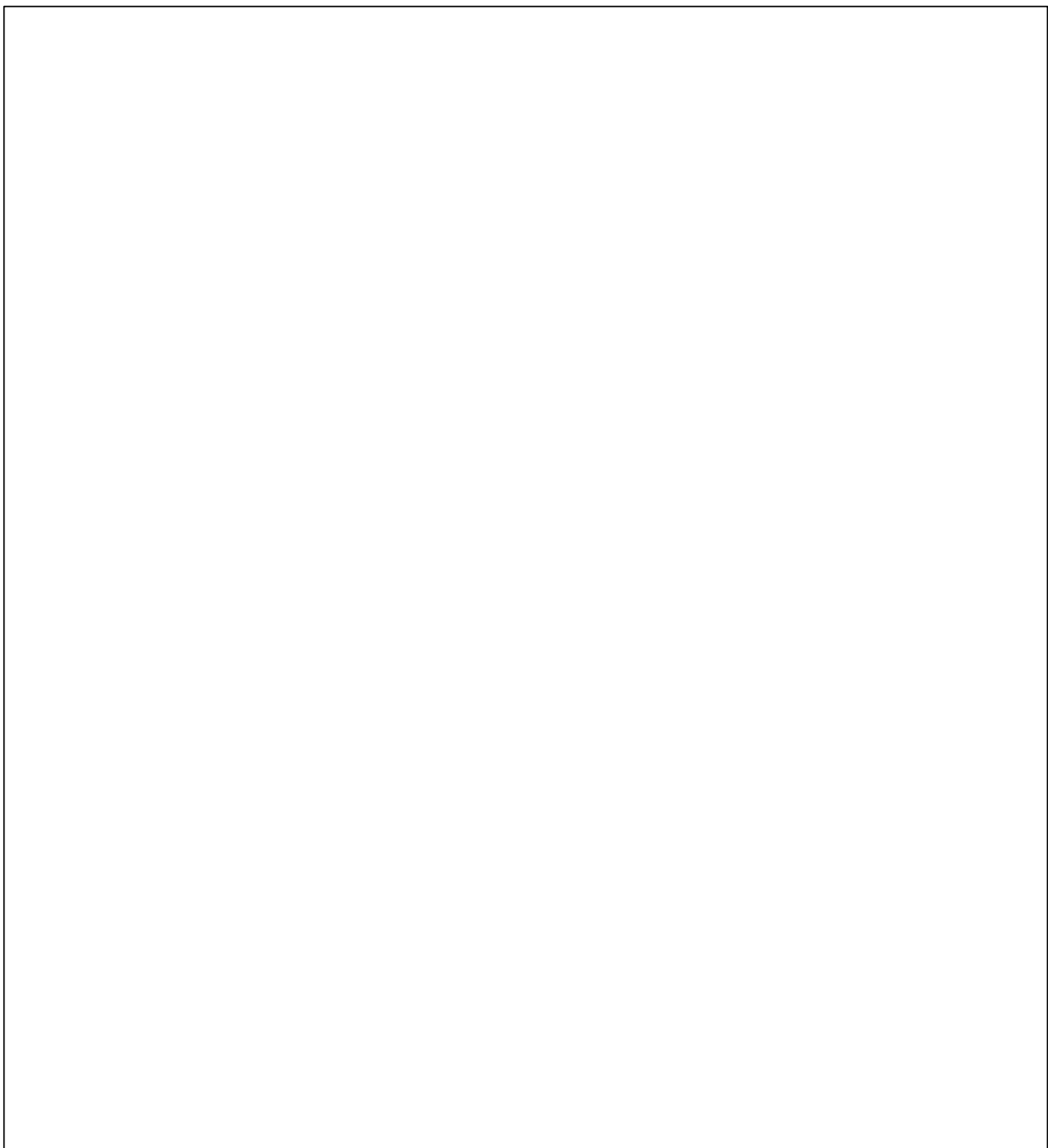
PRIMARY SOLDER PASTE

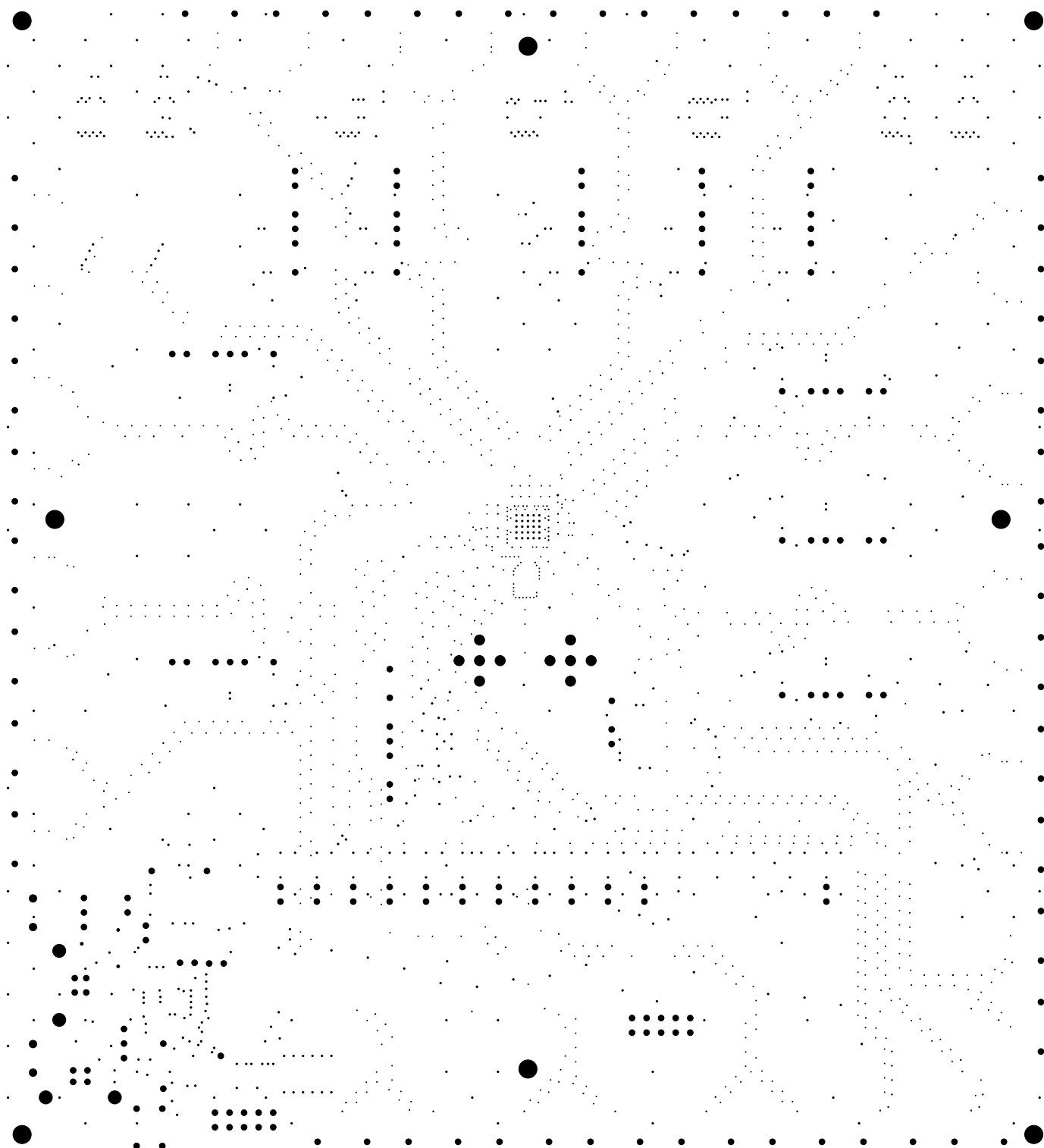




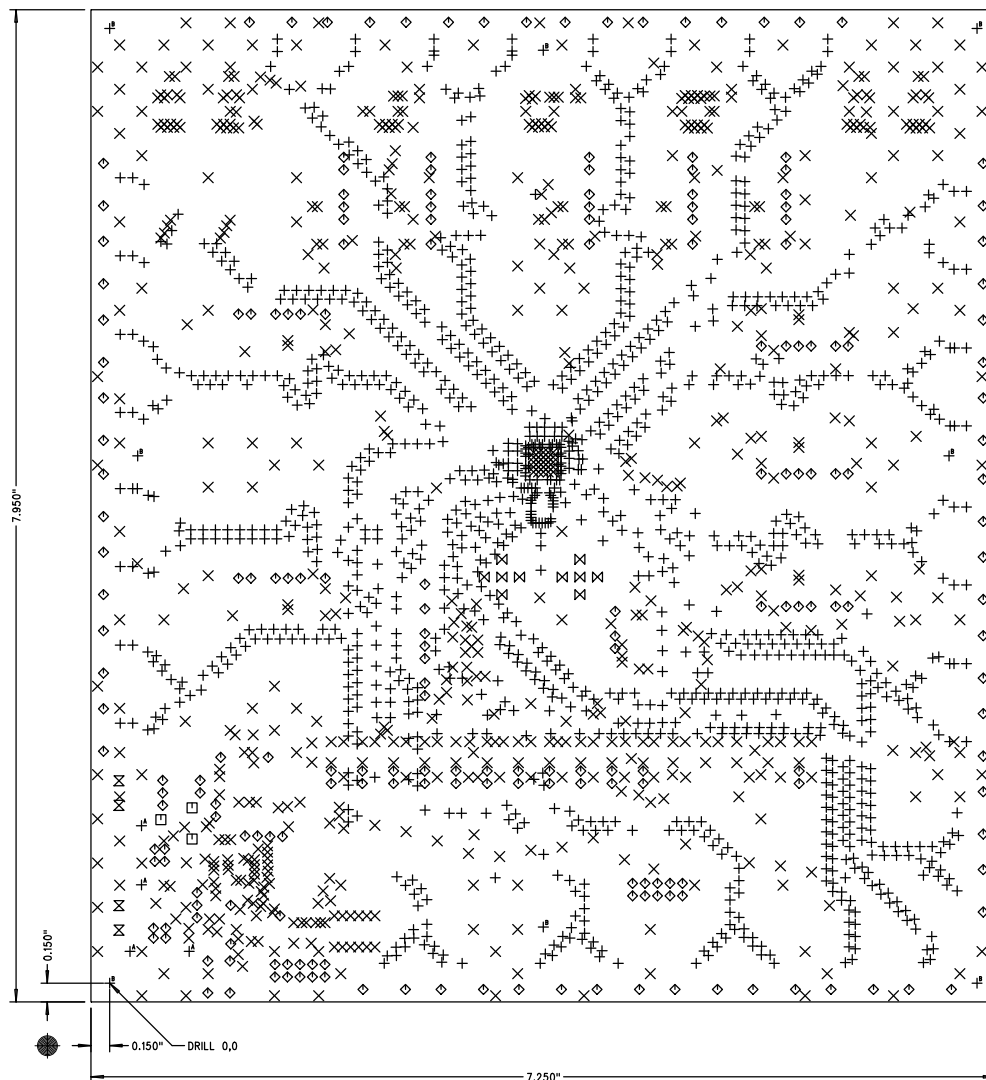
SECONDARY SOLDER PASTE







PRIMARY DRILL



NOTES : UNLESS OTHERWISE SPECIFIED

1. MANUFACTURE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
2. END PRODUCT FEATURES SHALL NOT VARY MORE THAN 20% FROM ARTWORK ORIGINALS.
3. MATERIAL SHALL BE COPPER CLAD ISOLA FR-406, Dk=3.9 & ISOLA FR-406 PREPREG, Dk=3.9 w/BALANCE OF MATERIAL TO BE COMPATIBLE FR-4 MEETING IPC-4101/26, PER LAYER STACKUP DETAIL.
4. COPPER WEIGHT SHALL BE 0.5 OZ./SQ. FT. BEFORE PLATING.
5. ALL PLATED THROUGH HOLES SHALL HAVE A MINIMUM OF 0.001" COPPER.
6. DRILL HOLE TOLERANCE AFTER PLATING SHALL BE ± 0.003 ".
7. MINIMUM ANNULAR RING SHALL BE 0.001".
8. MINIMUM ANNULAR RING AT EMERGENT CONDUCTORS SHALL BE 0.003".
9. FINAL PCB THICKNESS SHALL BE 0.062" $\pm 10\%$.
10. WARP/TWIST SHALL NOT EXCEED 1.0X.
11. FINISH SHALL BE LPI, BLUE SMOBC, ENIG BOTH SIDES.
12. SILKSCREEN WITH NONCONDUCTIVE WHITE EPOXY INK.
13. INTERNAL 0.175MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
EXTERNAL 0.275MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$.
TOP 0.762MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$ REF TO L03.
BOTTOM 0.762MM TRACES TO BE 50 OHM $Z_0 \pm 5\%$ REF TO L06.
14. VENDOR TO PROVIDE PCB MICRO-SECTION OF COUPON AREA & TDR TEST REPORT.
15. REFERENCE ADDITIONAL FAB NOTES IN FILE README.TXT


LAYER STACKUP

FILE NAMES

PRIMARY SILKSCREEN	534x-EB_PSS.PHO
PRIMARY SOLDERMASK	5345-EB_PSM.PHO
PRIMARY SIDE	5345-EB_PRI.PHO
FR-406 - 7MIL THK	
RF ROUTE/GND	5345-EB_L02.PHO
FR-406 - 7MIL THK	
GROUND PLANE	5345-EB_L03.PHO
FR-4 IPC-4101/26	
DIGITAL ROUTE/GND	5345-EB_L04.PHO
FR-4 IPC-4101/26	
VDD0x, VDD0UT, GND	5345-EB_L05.PHO
FR-4 IPC-4101/26	
GROUND PLANE	5345-EB_L06.PHO
FR-406 - 7MIL THK	
RF ROUTE/GND	5345-EB_L07.PHO
FR-406 - 7MIL THK	
SECONDARY SIDE	5345-EB_SEC.PHO
SECONDARY SOLDERMASK	5345-EB_SSM.PHO
SECONDARY SILKSCREEN	5345-EB_SSS.PHO

SCALE: NONE

SIZE	QTY	SYM	PLT	TOOL	TOL
0.006	1379	+	P	1	+0/-0.006
0.012	697	X	P	2	+0/-0.012
0.020	3	□	P	3	+/-0.003
0.040	225	◇	P	4	+/-0.003
0.052	4	⊗	P	5	+/-0.003
0.070	10	⊗	P	6	+/-0.003
0.091	4	A	P	7	+/-0.003
0.125	8	B	P	8	+/-0.003

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DIMENSIONS ARE IN INCHES AND APPLY AFTER FINISH DIMENSIONS IN BRACKETS () ARE IN MILLIMETERS INTERPRET DRAWING PER MIL-D-1000			COMPANY:  400 W CESAR CHAVEZ ST. AUSTIN, TX 78701 (512)416-8500 www.silabs.com		
TOLERANCES			NAME: Si5345-EB		
HOLE TOLERANCES PER 78027			SIZE PART NUMBER: B		
DECIMALS	ANGLES	SURFACES	SCALE 1:1		
.XX +/-	+/-	MICRONCHES	FABRICATION DRAWING		
.XXX +/-			SHEET 1 OF 1		
PART TO BE FREE OF BURRS			DO NOT SCALE DRAWING		
BREAK EDGES	BEND RADIUS	BEND RELIEF			
MAX	MAX	MAX			